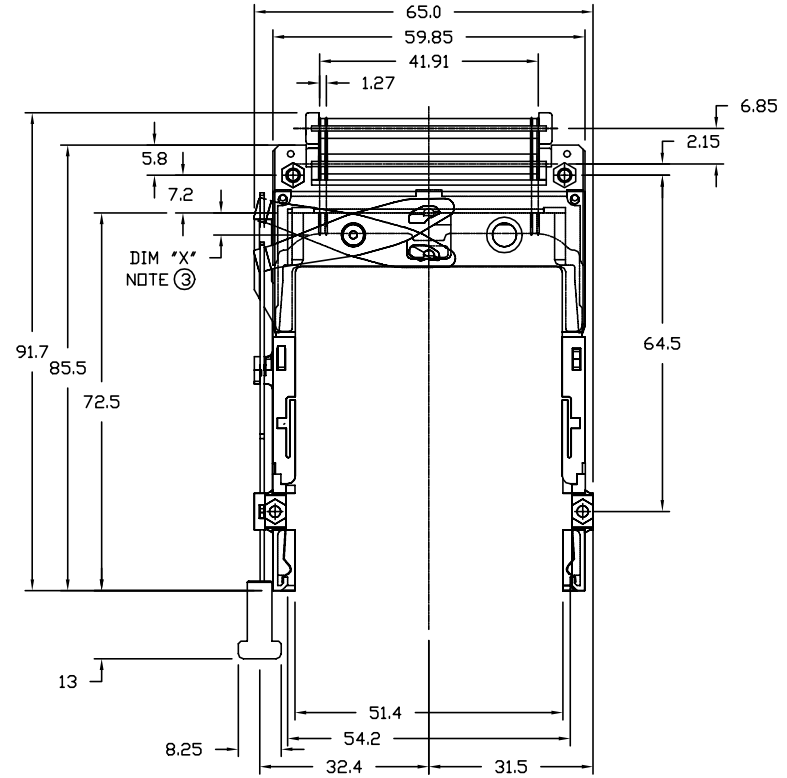
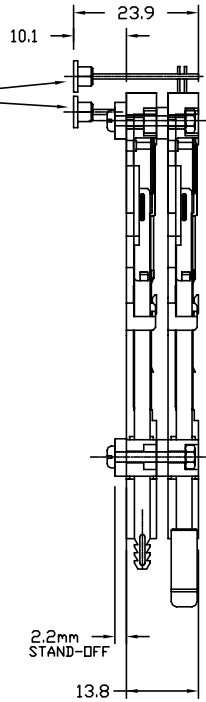


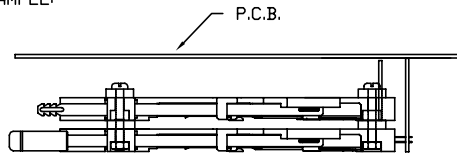
PRODUCT NO.
73408-003
73408-003LF

MATING RECEPTACLES SHOWN FOR APPLICATION CLARITY ONLY. MUST BE PURCHASED SEPARATELY. SEE NOTE 1.3

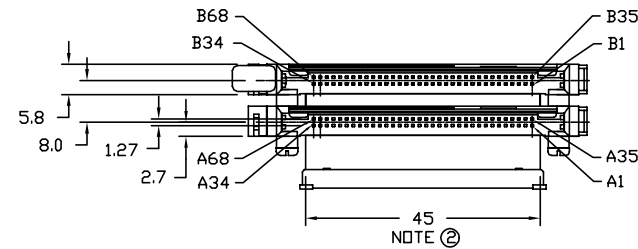


NOTE:

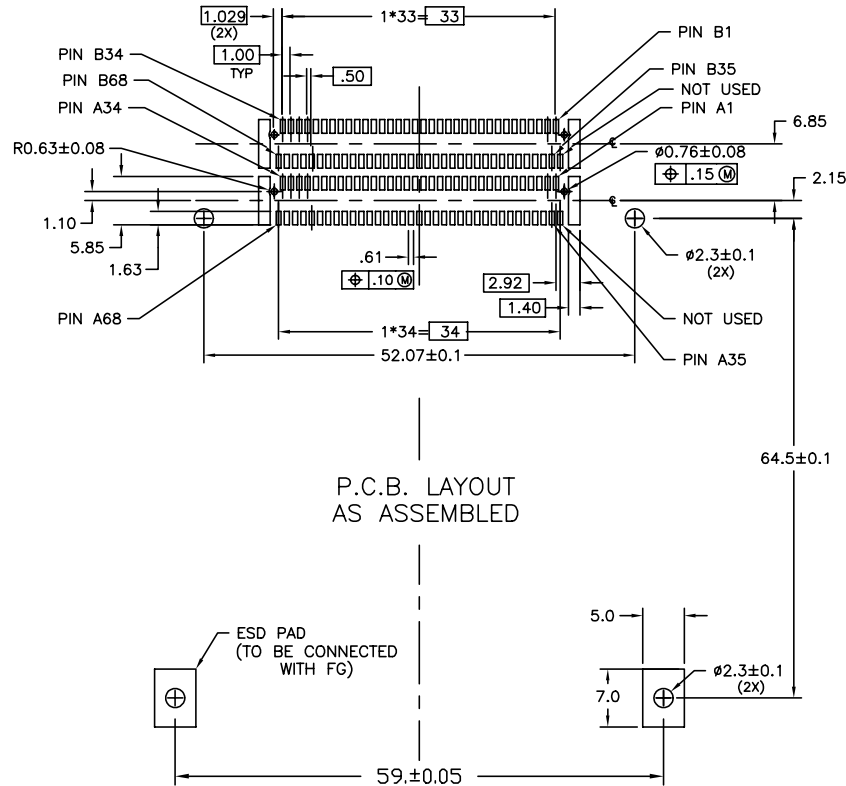
- 1. APPLICATION IS BELOW P.C.B. MOUNT
- ② BOARD WIDTH - 45mm MAX  
EXAMPLE:



VIEW AS INSTALLED



mat'l. code		surface <input checked="" type="checkbox"/> ISO1302 <input checked="" type="checkbox"/> tolerance <input checked="" type="checkbox"/> ISO1101 <input checked="" type="checkbox"/> ISO406		projection	product family			
l'tecn nodr		date			MCS			
c V12254 TFG		9/26/01			title			
D N05-0196 WB		07/05/05		MM	DOUBLE DECK VTB			
E BX-N-011413 ZK		04/02/12			HEADER ASSEMBLY			
		0°±2'		scale 1:1				
		dr R.GRAPE		3/10/97				
		enr D.BRANN		3/10/97				
		chr D.BRANN		3/10/97				
		appd D.BRANN		3/10/97				
sheet index	revision	E	E			dwg no	sheet 1 of 2	size
	1	2				73408		A4
						type Product Customer Drawing		



NOTES:

- 1 MATERIAL:
  - 1.1 HEADER ASSY:  
PLASTIC HOUSING: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 (WHITE) - BELOW PCB  
PIN: PHOSPHOR BRONZE  
PCB: FR4
  - 1.2 EJECT MECHANISM ASSY:  
PLASTIC GUIDE: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK  
PLASTIC PUSH-ROD BUTTON: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK  
COVER PLATE, EJECT PLATE, LINK ARM,  
PUSH ROD: STAINLESS STEEL  
EMI CONTACT: PHOSPHOR BRONZE
  - 1.3 MATING RECEPTACLE (91931-31169):  
PLASTIC: HIGH TEMPERATURE THERMOPLASTIC UL94V-0 BLACK  
CONTACT: BeCu
- 2 FINISH (PIN)  
UNDER PLATING: 0.5um MIN Ni  
CONTACT AREA: 0.076 µm MIN. GOLD  
  
SOLDER TAIL: 2.5umMIN Sn-Pb  
2.5umMIN PURE Sn ( FOR -003LF )
- 3 DIM "X"
 

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36,67	1,17,34,35,51,68
- 4 RECOMMENDED SCREW TORQUE: 1.0 TO 1.5 MAX in-lbs. (1.2-1.7 cm-kgs).
- 5 ELECTRICAL PERFORMANCE
  - A. CURRENT CAPACITY - 0.5 A PER CONTACT
  - B. CONTACT RESISTANCE (LOW LEVEL) - INITIALLY 40M OHMS;  
AFTER TEST 20M OHMS MAXIMUM CHANGE PER MIL-STD-1344A, METHOD 3002.1
  - C. WITHSTANDING VOLTAGE - NO SHORTING OR OTHER DAMAGE WHEN 500Vrms AC IS APPLIED FOR 1 MINUTE. CURRENT LEAKAGE 1mA MAXIMUM PER MIL-STD-202F, METHOD 301.
- 6 IF LEAD FREE P/N.THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.00MM MINIMUM THICK CIRCUIT BOARD.
- 7 IF LEAD FREE P/N.THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
- 8 LEAD FREE P/N PACKAGING MEETS GS-14-920 SPECIFICATION
- 9 PRODUCT SPEC:110-263

P.C.B. LAYOUT AS ASSEMBLED

mat'l. code		surface <input checked="" type="checkbox"/> ISO1302 <input checked="" type="checkbox"/> tolerance <input checked="" type="checkbox"/> ISO1101 <input checked="" type="checkbox"/> ISO406		projection	product family
ltr ecn nodr date		tolerances unless otherwise specified			MCS
E		angle	0.X±0.3	MM	DOUBLE DECK VTB HEADER ASSEMBLY
		0°±2'	0.XX±0.13	scale 1:1	
		dr	R.GRAPE	3/10/97	dwg no
		enr	D.BRANN	3/10/97	
		chr	D.BRANN	3/10/97	sheet 2 of 2
		appd	D.BRANN	3/10/97	size
sheet index		revision sheet 1		type Product Customer Drawing	

